

AMENDMENTS TO THE SPECIFICATION:

Please amend the specification as follows:

Page 18, replace the paragraph beginning on line 19 with the following amended paragraph.

Furthermore, the method for manufacturing a relief material for seamless printing according to claim 10 of the present invention further comprises a second removing step for removing a photosensitive resin cured layer in an area in which formation of the relief image in the carving step is unnecessary to a desired thickness in parallel with or after the shaping step in claim 9.

Page 23, replace the paragraph beginning on line 11 with the following amended paragraph.

Furthermore, the apparatus for manufacturing a relief material for seamless printing according to claim 18 of the present invention further comprises a working-tool holding pedestal mechanism capable of linearly moving a working-tool holding pedestal in the axis center direction of the workpiece and further includes at least one of a cutting mechanism, grinding mechanism, and polishing mechanism capable of linearly moving the working tool fixed by the holding pedestal in the direction vertical to the axis center of the workpiece in claim 16 or 17.

Page 23, lines 25-27, through page 24, lines 1-6, please amend this paragraph as follows:

Furthermore, the apparatus for manufacturing a relief material for seamless printing according to claim 19 of the present invention is characterized by setting a moving-position detecting mechanism capable of detecting a moving position at the time

of the linear movement to at least one of the resin supplying mechanism, resin applying smoothing mechanism, exposing mechanism, working-tool holding pedestal mechanism, cutting mechanism, grinding mechanism, and polishing mechanism in any one of claims 16 to 18.

Page 25, replace the paragraph beginning on line 6 with the following amended paragraph:

Furthermore, the apparatus for manufacturing a relief material for seamless printing according to claim 22 of the present invention is characterized in that the second resin supplying mechanism is a resin supplying nozzle having at least one or more resin supplying cutting-off control mechanisms connected with either of a housing vessel having resin moving means for moving liquid-state photosensitive resin and a storing apparatus and the resin supplying means is a constant-quantity pressure pump having a constant-quantity supplying characteristic for unit time and a mechanism for removing bubbles in the liquid-state photosensitive resin is set between either of the housing vessel and the storing apparatus and the resin supplying nozzle in any one of claims 16 to 21.

Page 25, replace the paragraph beginning on line 23 with the following amended paragraph:

Furthermore, the apparatus for manufacturing a relief material for seamless printing according to claim 23 of the present invention further comprises a signal converting mechanism for receiving and storing a digital image recording signal and converting the stored signal into a light-modulation control signal of an infrared laser beam, a laser generating mechanism for generating one or more infrared

laser beams, a control mechanism for independently setting the infrared intensity and applying time every infrared laser beam, and a laser carving head mechanism having optical system means fixed by the holding pedestal to focus the infrared laser beam on the surface of a photosensitive resin cured layer obtained by curing liquid-state photosensitive resin on the outer periphery of the workpiece in any one of claims 16 to 22.

Page 33, replace the paragraph beginning on line 1 with the following amended paragraph:

However, as shown in Fig. 8, it is also possible to substitute the resin supplying nozzle with a unmovable liquid-state photosensitive resin supplying unit 600 by using a liquid-state photosensitive resin housing tank 610, a constant-quantity pressure pump 620 for moving a constant quantity of the liquid-state photosensitive resin 10, a defoaming mechanism 630 for defoaming bubbles contained in the liquid-state photosensitive resin 10, a resin supplying header 640, and a switching electromagnetic valve 650 for controlling supply and stop of the liquid-state photosensitive resin 10. Moreover, it is preferable that the capacity of the housed liquid-state photosensitive resin 10 can be measured by a level sensor and a temperature control mechanism for stabilizing the temperature (final purpose is stabilization of viscosity) of the liquid-state photosensitive resin 10 in the supply route of the liquid-state photosensitive resin 10 from the tank 610 up to the resin supplying nozzle.